

Docket No. 219.40430X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

H. XIE, et al.

Serial No.:

09/964,494

Filed:

September 28, 2001

For:

ARRANGEMENTS TO INCREASE STRUCTURAL RIGIDITY OF

SEMICONDUCTOR PACKAGE

Art Unit:

2811

Examiner:

UNKNOWN

PRELIMINARY AMENDMENT

COMMISSIONER OF PATENTS Washington, DC 20231

March 19, 2002

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

IN THE CLAIMS:

Please amend claims 1-2, 5-6, 8-11, 13-18, 21-22, 24-27, 31-34, 37-38, 40-43, 47-49 and add new claims 50-62 as follows. Note that the full text of all claims (including those not being amended within this paper) may also be included to provide the convenience of a complete set of claims for easy review:

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